

***Inforce 68A1<sup>™</sup>***  
***Hardware Reference Manual***

***003835 Rev A***  
***November 19, 2021***

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# Preface

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This Hardware Reference Manual explains hardware and mechanical specifications of the Inforce 68A1 board.

## Intended Audience

This Hardware Reference Manual is intended for technically qualified personnel. It is not intended for general audiences.

## Document Organization

The chapters in this document are arranged as follows:

1. Scope
2. Hardware Specifications
3. Mechanical Specifications
4. Appendix A
5. Contact Information

## Conventions

The following conventions are used in this document:



### CAUTION

Cautions warn the user about how to prevent damage to hardware or loss of data.



### NOTE

Notes call attention to important information.

## Note

- This document is subject to change without notice.
- Carrier parts are shown in some of the sections for better understanding.

## Support Information

Every effort has been made to ensure the accuracy of the Hardware Reference Manual. If you have any comments, questions, or ideas regarding this document, contact SMART Wireless's technical support at: [TechSupport-wc@smartwirelesscompute.com](mailto:TechSupport-wc@smartwirelesscompute.com)

# Terminology

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The table below gives descriptions to some common terms used in the Hardware Reference Manual.

<b>Term</b>	<b>Description</b>
BLE	Bluetooth Low Energy
bps	Bits Per Second
CSI	Camera Serial Interface
DDR	Double Data Rate
DS	Default Speed
DSI	Display Serial Interface
DSP	Digital Signal Processing
GPIO	General-Purpose Input/Output
GPU	Graphical Processing Unit
HPH	Head Phone
HS	High Speed
HVX	Hexagon Vector Extensions
I2C	Inter-Integrated Circuit
JTAG	Joint Test Action Group
LDO	Low Drop Out
LED	Light-Emitting Diode
LPDDR	Low-power DDR
MIC	Microphone
MIPI	Mobile Industry Processor Interface
OTG	On The Go
PCIe	Peripheral Component Interconnect Express
PMIC	Power Management IC
PoP	Package On Package
PU	Pull Up
RF	Radio Frequency
SDC	Secure digital controller
SDIO	Secured Data Input/output
SDR	Single Data Rate
SLIM bus	Serial Low-power Inter-chip Media Bus
SOC	System On Chip
SOM	System on Module
SPI	Serial Peripheral Interface
SPMI	System power management interface
UART	Universal Asynchronous Receiver Transmitter
USB	Universal Serial Bus
WLAN	Wireless local area network

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# 1. SCOPE

This document describes the electrical, mechanical, and functional specifications of Qualcomm QCS8250-based Inforce 68A1 SOM.

## Overview

The table below presents a brief overview of Inforce 68A1 board.

**Table 1: Inforce 68A1 Board Overview**

<b>Processor</b>		
Processor	Qualcomm® QCS8250 Processor (PoP package)	
<b>Memory Devices</b>		
Main Memory and Storage	8GB LPDDR5, 5500 MB/s 64GB UFS 2.1	
<b>SOM Interfaces</b>		
Interfaces	1× USB v3.1 Gen 2 (Host) 1× USB v3.1 Gen 2 Type C (Device mode, Host mode, DP, Debug) 2× 4 lane MIPI-DSI 1× UART (Debug) 5× 4 Lane MIPI-CSI+ 1× 2 Lane MIPI-CSI 3× Camera Control I2C, 1× PCIe Gen 3 2× M4F4-WiFi/BT,	1× 4 bit SDC for SDcard 1× Line Out 1× Ear out 3× Mic In 1× Headphone Out, 1× LPI_MI2S2 / Soundwire and DMIC 2X DMIC / 1x LPI_MI2S1 1× MI2S2 1× MI2S0/GPIO 1× Sensor Core I2C 2× Regulator Out
<b>Form Factor</b>		
Mechanical	50mm×35mm Tolerance +/- 0.2mm	
<b>Power</b>		
Power Input	VBAT (+3.2 to +4.5V)	
<b>Others</b>		
Temperature Specification	Commercial Grade	



### NOTE

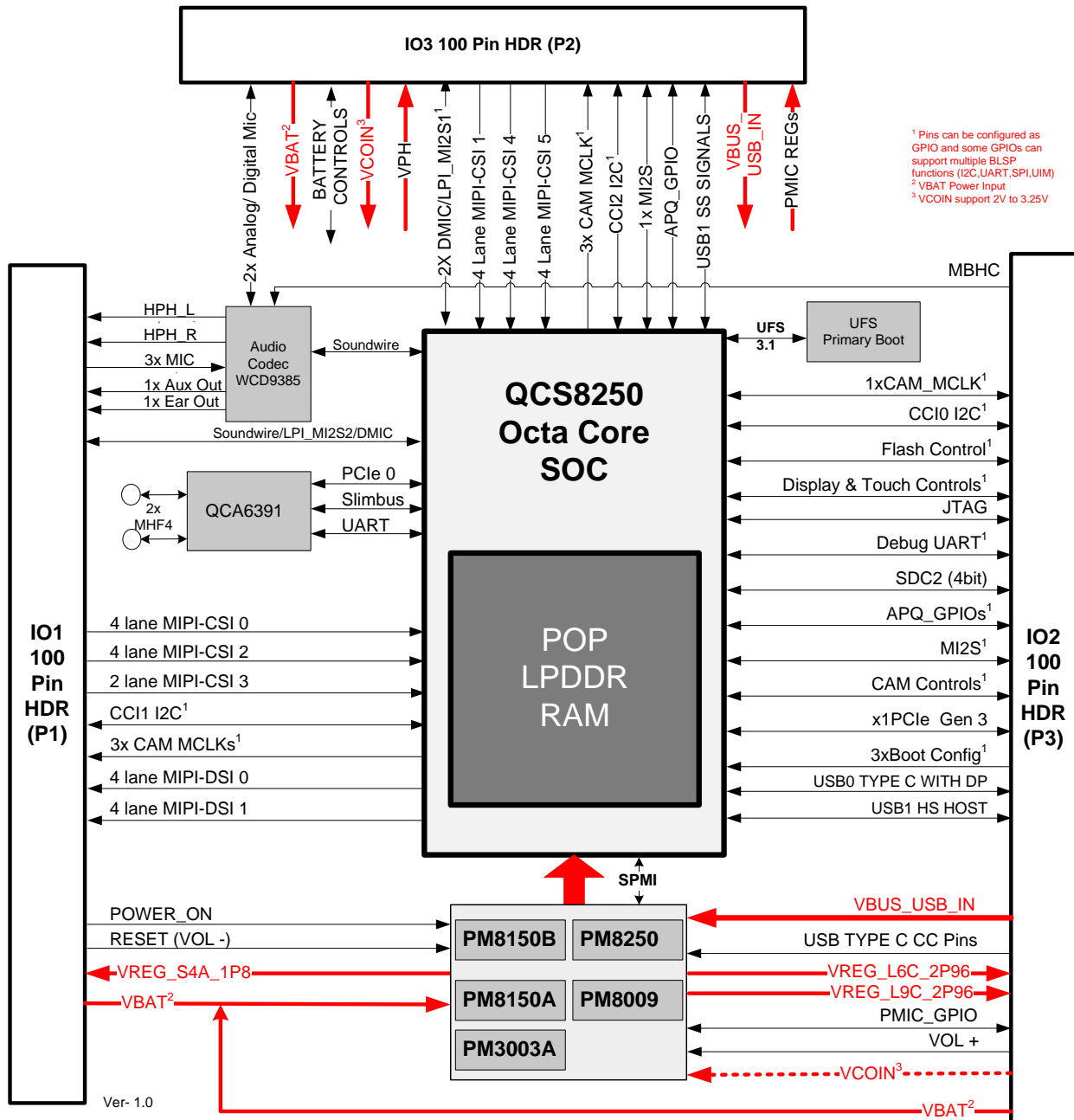
1. MI2S0 muxed with QUP and selected GPIO\_2 to high.

# 2. HARDWARE SPECIFICATIONS

## 2.1 ARCHITECTURE

The functional diagram of the Inforce 68A1 SOM is shown below.

Figure 1: Block Diagram

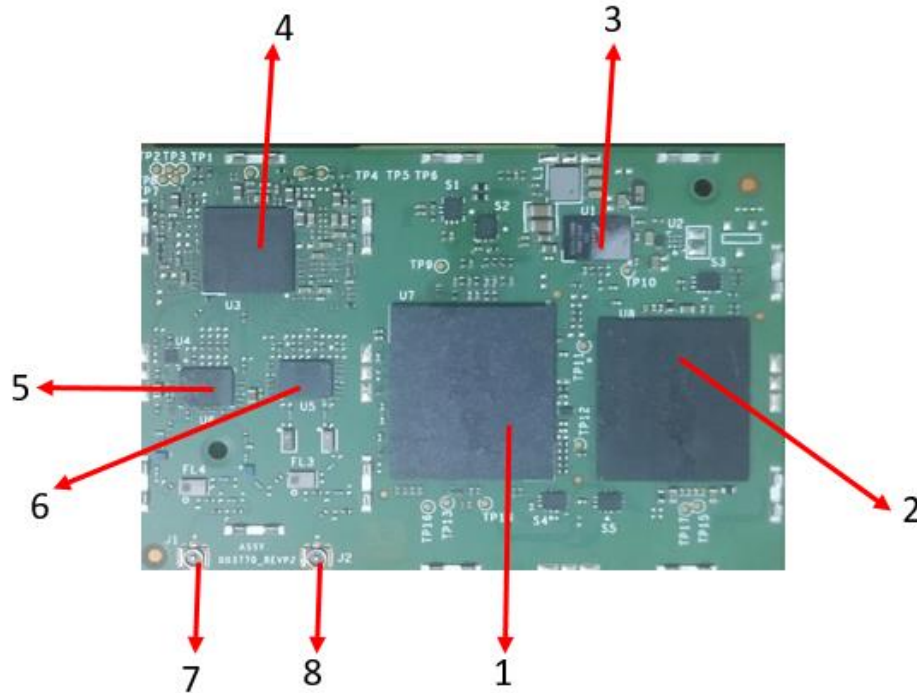


<sup>1</sup> Pins can be configured as GPIO and some GPIOs can support multiple BLSIP functions (I2C,UART,SPI,UIM)  
<sup>2</sup> VBAT Power Input  
<sup>3</sup> VCOIN support 2V to 3.25V

### 2.1.1 SYSTEM OVERVIEW

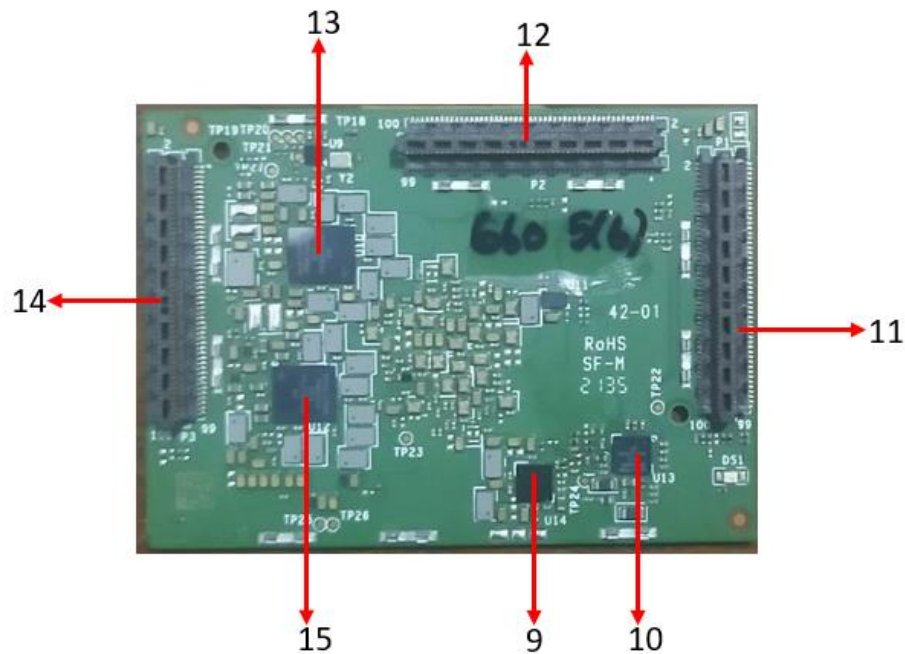
The Inforce 68A1 SOM is based on the Qualcomm Octa-core QCS8250.

**Figure 2: Inforce 68A1 Board (Top Side)**



**Table 2: Inforce 68A1 Board Locations**

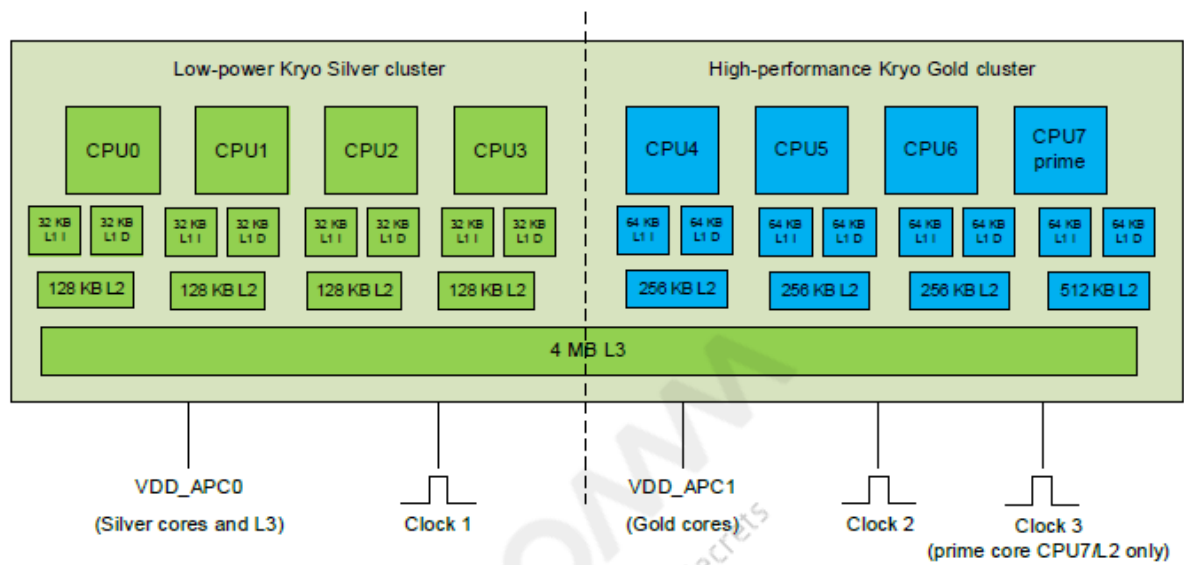
No.	Description
1	QCS8250 + POP LPDDR5
2	UFS
3	PMIC PM8150B
4	WIFI QCA6391
5	FEM/2.4GHZ
6	FEM/5GHZ
7	Wi-Fi /BT Chain 1 MHF4 connector
8	Wi-Fi /BT Chain 0 MHF4 connector
9	PIMIC PM-8009
10	Audio Codec WCD9385
11	SOM Connector P1 (IO interface 1)
12	SOM Connector P2 (IO interface 3)
13	PIMIC PM8150A
14	SOM Connector P3 (IO interface 2)
15	PMIC PM8250

**Figure 3: Inforce 68A1 Board (Bottom Side)**

### 2.1.2 QCS8250 FEATURES

- Customized 64-bit Arm v8.2-compliant octa-core Kryo applications processor
- Qualcomm® Adreno™ 650 graphics processing unit (GPU)
- Audio Qualcomm® Hexagon™ DSP for LPASS
- Qualcomm® Hexagon™ DSP with quad Hexagon Vector eXtensions (HVX) processor for vision processing and machine learning
- Qualcomm Spectra™ 480 image processing engine for the ultimate photography and videography experiences
- Adreno 665 VPU for high-quality, ultra HD video encode and decode
- Adreno 995 DPU for on-device and external ultra HD display support
- Low-power audio subsystem combined with the Qualcomm Aqstic™ Audio Technologies WCD9385 audio codec for low power voice processing and audiophile quality audio playback
- Eight Kryo cores organized into two clusters:
  - Four high-performance Kryo cores – Gold cluster
    - ◆ Three Gold cores targeting 2.5 GHz
    - ◆ One Gold prime core targeting 2.8 GHz
  - Four low-power Kryo cores targeting 1.7 GHz for quad core – Silver cluster
- Dedicated L2 cache per Kryo Gold core and per Kryo Silver core

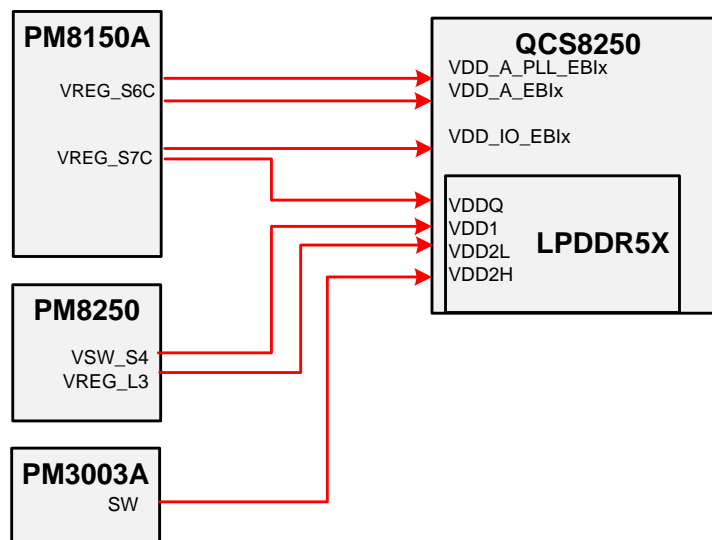
Figure 4: Kryo Cores



### 2.1.3 LPDDR5 INTERFACE

- Single x16 channel/die
- 1 Gig x 64 (4 channels x16 I/O)
- Supports clock up to 2.75GHz
- Memory mounted on top of QCS8250 (PoP package)
- LPDDR5 power via QCS8250 from PMIC

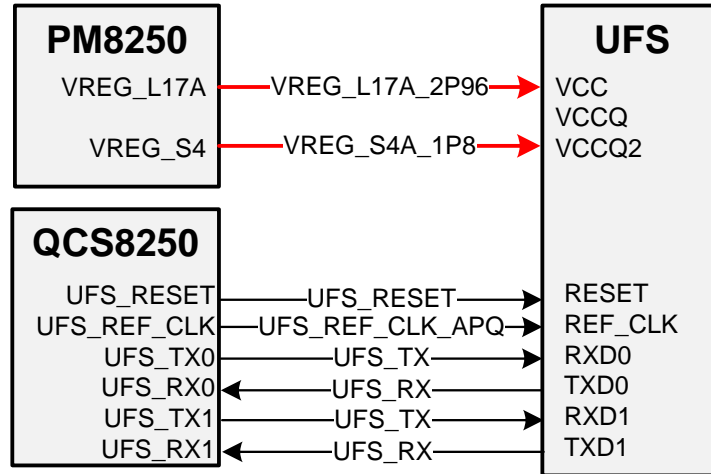
Figure 5: LPDDR5 Power



### 2.1.4 UFS INTERFACE

- UFS v2.1
- Gear 3 Two lane
- M-PHY v3.1

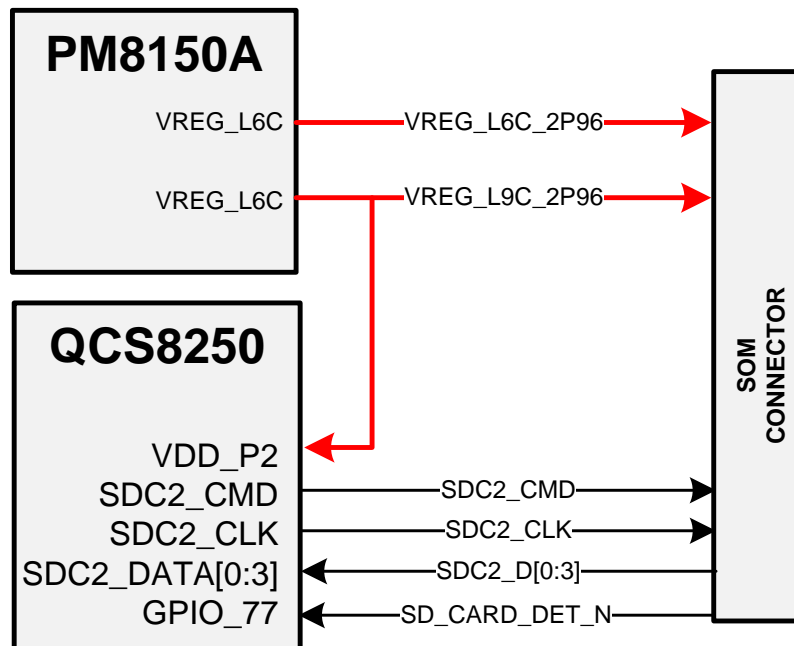
Figure 6: UFS



## 2.1.5 MICROSD CARD INTERFACE

- Supports SDIO (Ver. 3.0) interface for supporting standard micro SD cards.
- SDC2 Interface
- 4-bit Data Bus
- 208MHz Maximum Clock
- VREG\_L6C\_2P96 IO reference Dual voltage 1.8V or 2.95V interface
- VREG\_L9C\_2P96 SDcard power, Maximum current 800mA
- Supported modes:
  - 2.95 V – DS, HS
  - 1.8 V – SDR12, SDR25, SDR50, SDR104, DDR50

**Figure 7: SD Card Interface**



## 2.1.6 AUDIO INTERFACES

- Soundwire/LPI\_MI2S2/DMIC
- 2X DMIC/LPI\_MI2S1
- 1x MI2S2
- 1x MI2S0/GPIO

### WCD9385 CODEC

- **1× Line Out**
  - 1x Differential Mode optional for Aux-out 1
- **1x Ear Out**
  - 1x Differential
  - 32ohm Drive
- **1× Headphone Out**
  - High performance stereo single-ended Class-H headphone driver to drive 16 or 32  $\Omega$  loads
  - 1 Vrms ground referenced output capless output
  - Supports 32 bits data and up to 384 kHz sampling rate
- **3× Analog Mic In**
  - Single-ended Audio in
  - Capless input
  - MIC biased
- **2x Analog/ Digital\_Mic In**
  - 48 kHz, DMIC CLK frequency = 2.4 MHz,
- **Soundwire communication to Processor**



Figure 8: WCD9385 Implementation

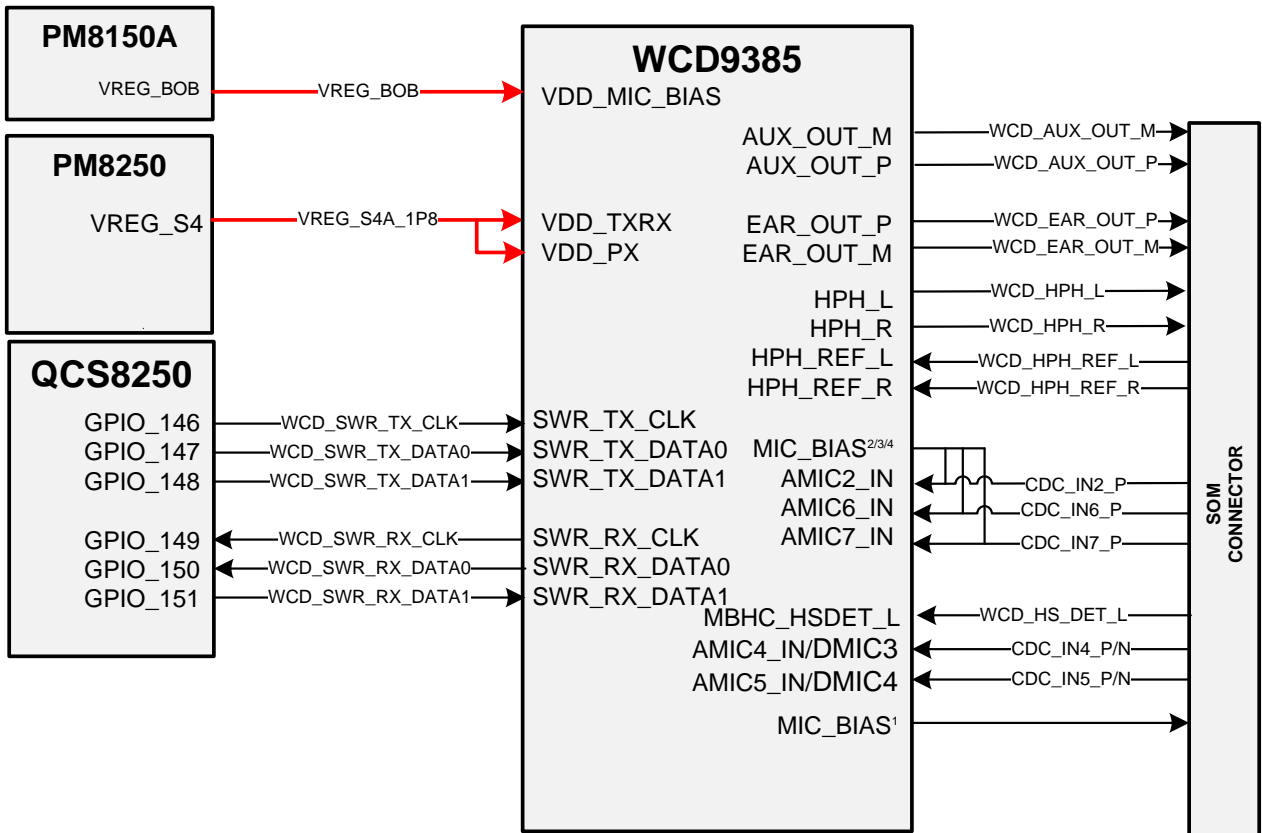
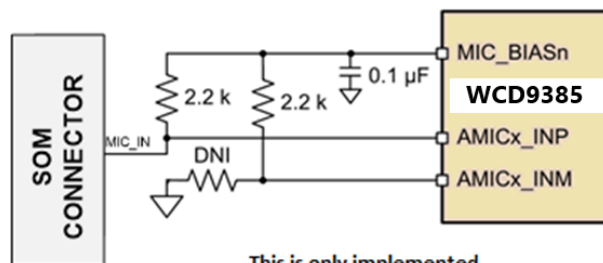


Figure 9: MIC Input



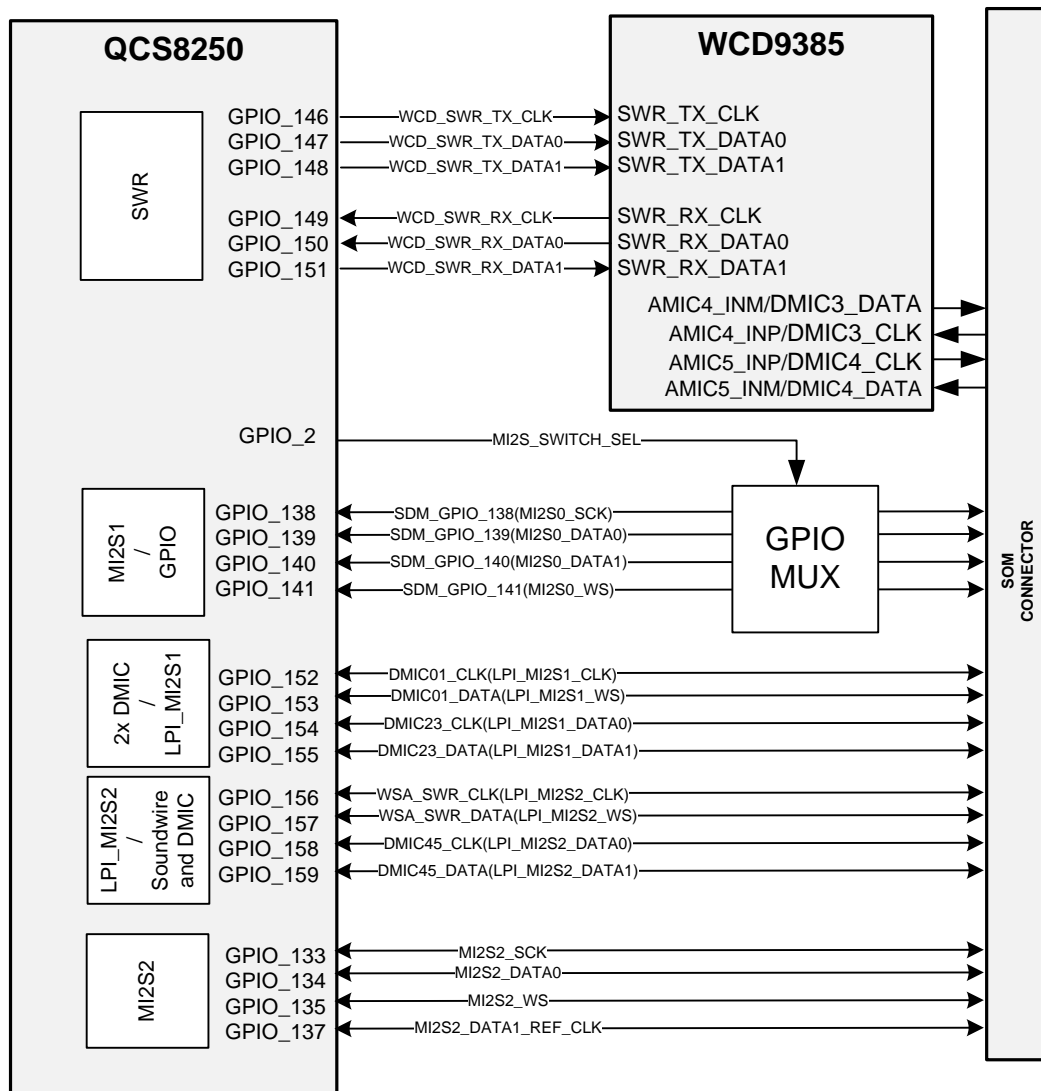
This is only implemented  
for x 2,6,7  
n 2,3,4

## DIGITAL AUDIO INTERFACES

QCS8250 supports various digital audio interfaces

- LPI\_MI2S2 / Soundwire and DMIC
- 2X DMIC/LPI\_MI2S1
- 1x MI2S2
- MI2S0/GPIO

**Figure 10: Digital Audio Interfaces**



## MI2S

- MI2S0 muxed with QUP and selected GPIO\_2 to high

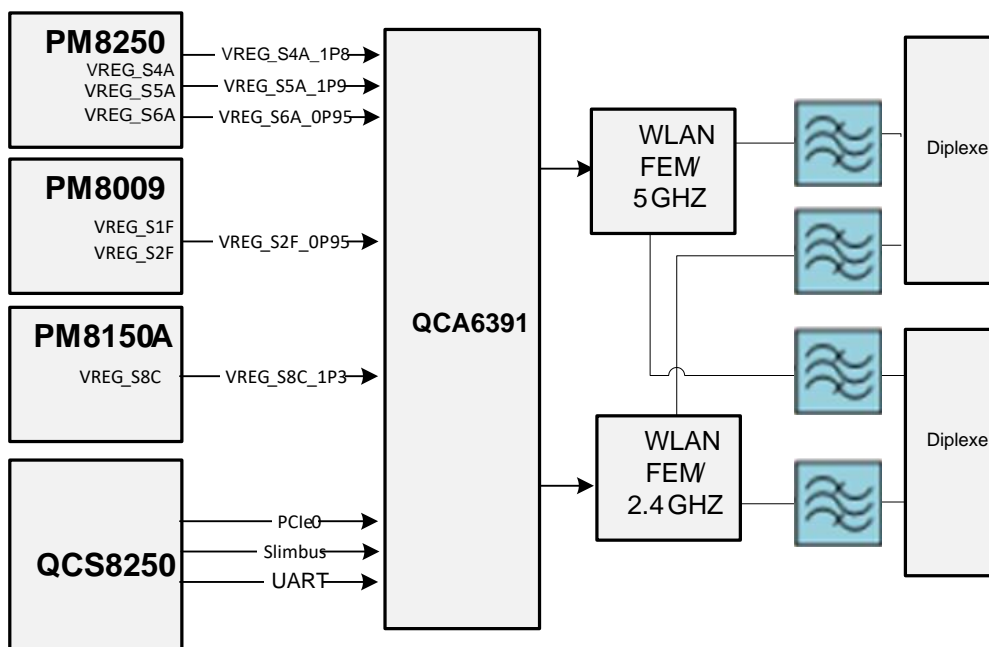
**Table 3: MI2S MUX**

Pin	GPIO_2 = 0 (QUP)	GPIO_2 = 1 (MI2S)
SDM_GPIO_54_OR_138	GPIO_54	GPIO_138 MI2S0_SCK
SDM_GPIO_55_OR_141	GPIO_55	GPIO_141 MI2S0_WS
SDM_GPIO_52_OR_139	GPIO_52	GPIO_139 MI2S0_DATA0
SDM_GPIO_53_OR_140	GPIO_53	GPIO_140 MI2S0_DATA1

## 2.1.7 WI-FI AND BLUETOOTH INTERFACE

- QCA6391 Dual-Band 2x2 MIMO DBS 802.11ax + Bluetooth
- WLAN: 802.11a/b/g/n/ac/ax, MU-MIMO
- Dual Band Simultaneous (DBS) with dual MAC, up to 1774.5 Mbps data rate (2x2+2x2 11ax DBS)
- Dual band 2.4G/5G chains
- Bluetooth v5.1 and ANT+, Bluetooth Milan ready
- Flexible interface Slimbus/PCM/I2S for BT audio
- 2x MHF4 Connector for external antenna

**Figure 11: Wi-Fi and Bluetooth Implementation**



## 2.1.8 DISPLAY INTERFACES

- The QCS8250 chipset can support 5040 × 2160 11 at 60 Hz (or 120 Hz in VR mode), up to 30 bpp.
- Two 4-lane DSI D-PHY 1.2 at 2.5 Gbps per lane
- Two 2560 × 2560 1 at 120 Hz for dual-panel VR displays, up to 30 bpp
- DisplayPort v1.4 at 8.1 Gbps/lane over Type-C with support for MST and VESA DSC v1.1 and FEC (USB3 and USB2 concurrency supported)
- Miracast – up to 4K60
- Adreno GPU 650, Fmax at 587 MHz – 4K 60 fps UI or 2X 2K 60 fps UI

### MIPI-DSI INTERFACE

- Two 4-lane; DSI D-PHY 1.2
- VESA DSC 1.1

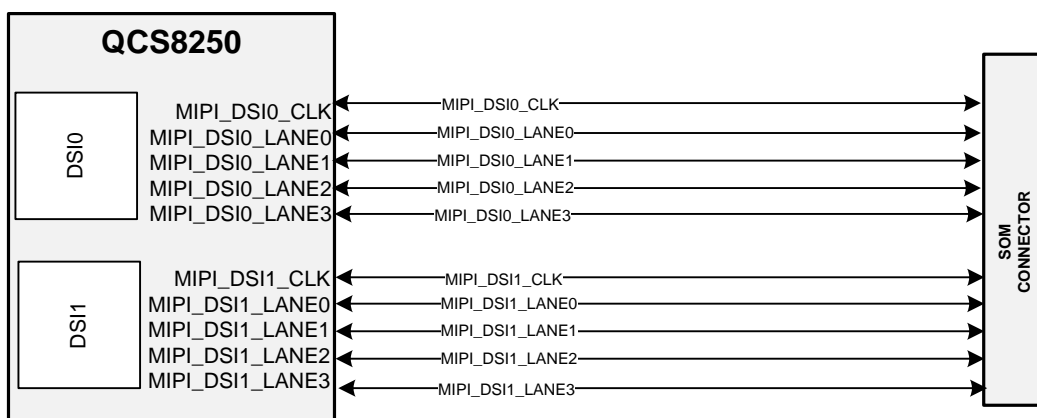
#### Display Controls

- Display Reset : GPIO\_38
- Backlight Enable Output : GPIO\_39
- PWM capable Output : PM8150A\_GPIO\_06

#### Touch screen Support

- Controls : QUP 13 I2C
- I2C Pull ups (2.2K to 1.8V) are present in the SOM
- Reset : GPIO\_42
- Interrupt : GPIO\_59

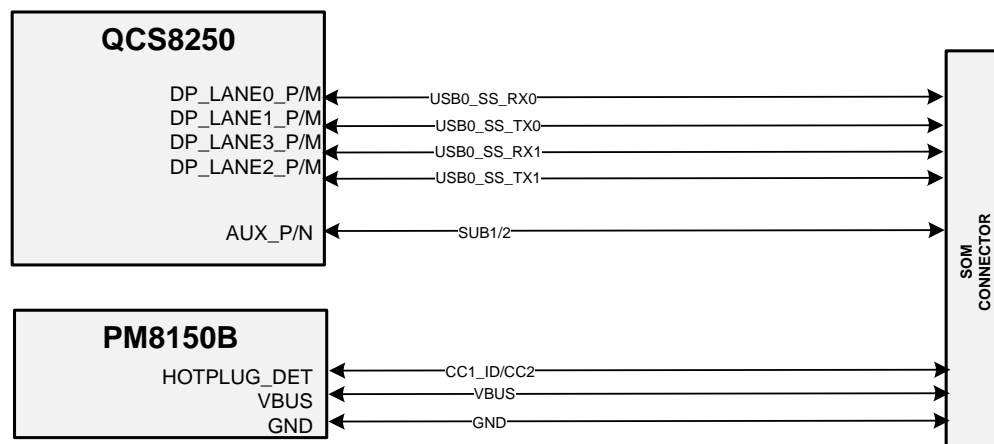
Figure 12: MIPI-DSI Interface



## DP INTERFACE

- DisplayPort v1.4 at 8.1 Gbps/lane over Type-C with support for MST and VESA DSC v1.1 and FEC (USB3 and USB2 concurrency supported)
- USB mode and DisplayPort mode can be simultaneously operating at USB 3 (10 Gbps) and DisplayPort (8.1 Gbps)
- In Display Port mode
  - The SM8250 can support up to 4-lane DisplayPort, 8.1 Gbps/lane
  - The USB 2.0 can be supported simultaneously.
  - USB 3.1 can be supported simultaneously.

**Figure 13: Type C Display port Interface**



## 2.1.9 CAMERA INTERFACES

- 5x 4-lane,+ 1x 2-lane camera interface
- Qualcomm Spectra 480 ISP to support up to 12 cameras by D-PHY and 18 cameras by C-PHY (seven concurrent)
- Real-time sensor input resolution: 25 + 25 + 2 + 2 + 2 + 2 + 2
- 64 MP 30 fps ZSL with a dual ISP
- Hardware 2PD support and improved face detection
- 4K120 camcorder and improved spatial noise reduction
- MIPI CSI configurable in 4 + 4 + 4 + 4 + 4 + 4 configuration
- D-PHY v1.2: 2.5 Gbps/lane on four lanes per port
- C-PHY v1.2: 10.26 Gbps/trio on three trios per port

## D-PHY, C-PHY SUPPORT

- Five 4-lane CSI D-PHY 1.2 at 2.5 Gbps per lane or Four 3-trio C-PHY 1.2 at 30.78 Gbps.
- One 2-lane CSI D-PHY
- C-PHY 1.2 is supported on the QCS8250 chipset, which uses single-ended signaling with an embedded clock (three wires per trio).

**Table 4: CPHY Pin out**

<b>DPHY PIN OUT</b>	<b>CPHY PIN OUT</b>
MIPI_CSIX_CLK_P	Do not connect (DNC)
MIPI_CSIX_CLK_N	CSIX_A0_CLK_M
MIPI_CSIX_LANE0_P	CSIX_B0_LN0_P
MIPI_CSIX_LANE0_N	CSIX_C0_LN0_M
MIPI_CSIX_LANE1_P	CSIX_A1_LN1_P
MIPI_CSIX_LANE1_N	CSIX_B1_LN1_M
MIPI_CSIX_LANE2_P	CSIX_C1_LN2_P
MIPI_CSIX_LANE2_N	CSIX_A2_LN2_M
MIPI_CSIX_LANE3_P	CSIX_B2_LN3_P
MIPI_CSIX_LANE3_N	CSIX_C2_LN3_M

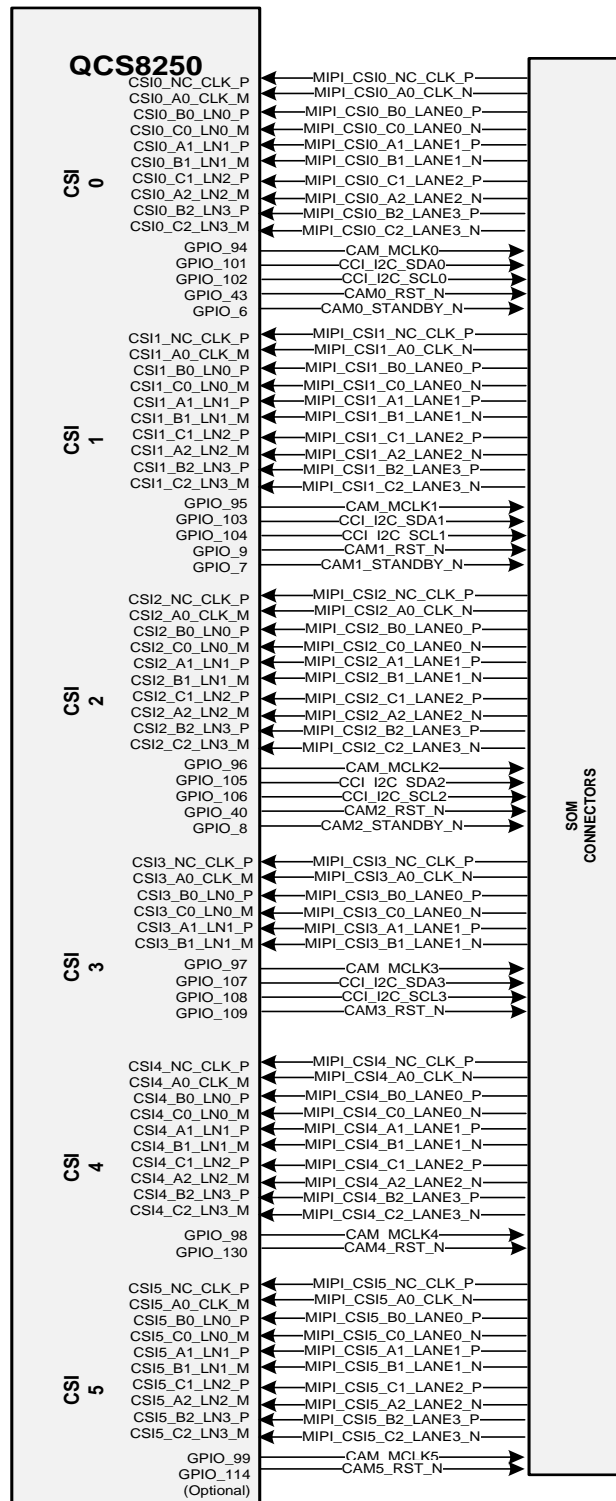
## Controls

- 2x Flash control GPIOs
- Reset & Mclock for each camera interface
- Depending on the use case cameras can either share the CCI\_I2C
- Additional CAM\_MLCK6 for multiple camera option

**Table 5: Camera PHY Interface**

<b>Camera</b>	<b>Lane</b>	<b>PHY</b>
CSI0	4	C/D PHY
CSI1	4	C/D PHY
CSI2	4	C/D PHY
CSI3	2	D PHY Only
CSI4	4	C/D PHY
CSI5	4	D PHY Only

Figure 14: MIPI CSI Interface



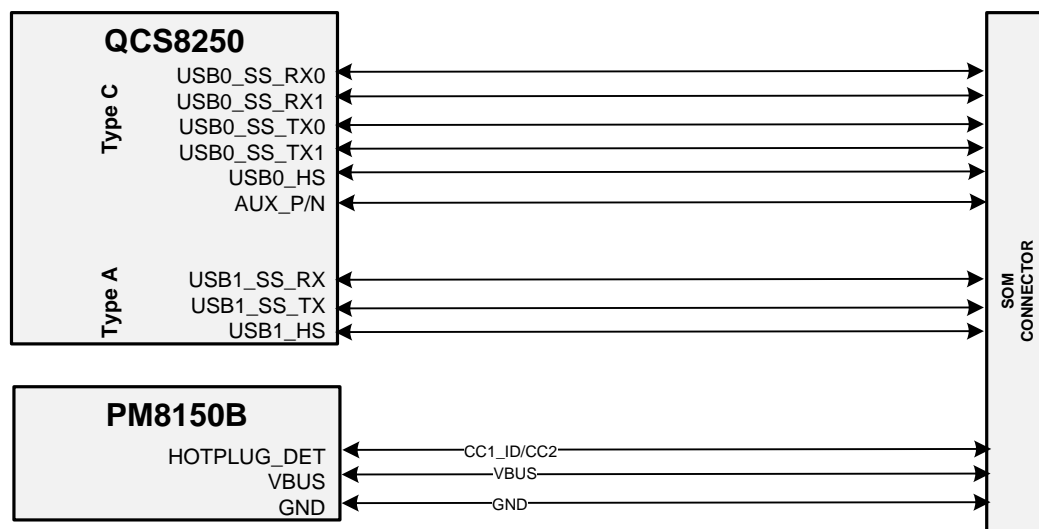
**NOTE**

- Do not use CCI I2Cs as general-purpose I2C ports
- I2C Pulls ups are present in the SOM

## 2.1.10 USB INTERFACE

- 2x USB 3.1 super-speed (USB0\_SS & USB1\_SS) and 2x USB 2.0 high-speed (USB1\_HS & USB2\_HS)
- Up to 480Mbps in USB2.0 mode
- Up to 10Gbps in USB3.1 mode
- USB Type C in default device mode and ADB is available on this port

**Figure 15: USB Interface**

**NOTE**

- Series capacitors are present on the TX lines

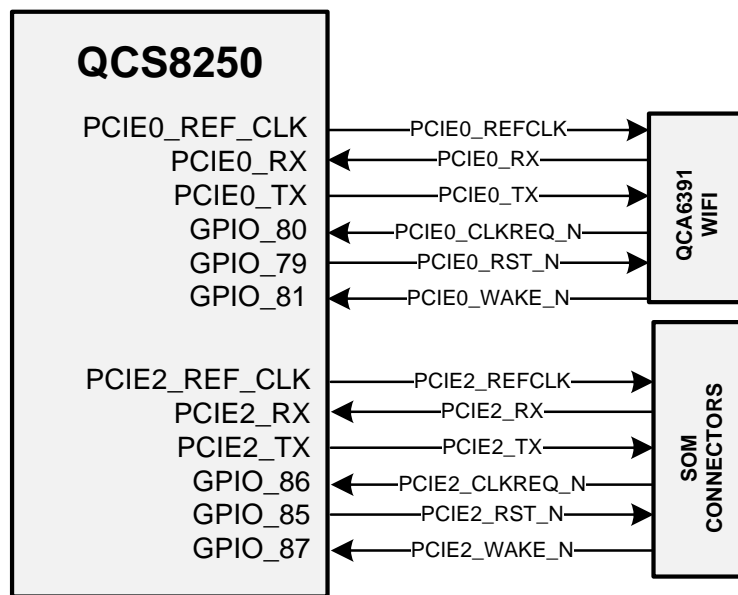


## 2.1.11 PCIE

### Specifications

- QCS8250 has three PCIe Interfaces
- PCIe0 is a Gen 3 1-lane interface
- PCIe1 is a Gen 3 2-lane interface (PCIe1 is not made available from the SoM)
- PCIe2 is a Gen 3 2-lane interface

**Figure 16: PCIE Interface**



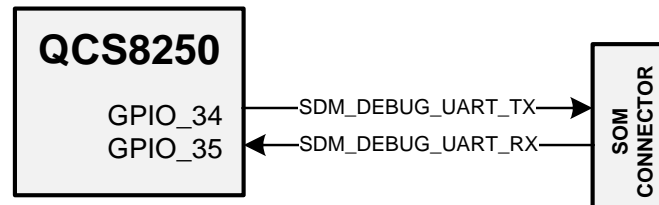
#### NOTE

Series capacitors are present on the TX lines

## 2.1.12 DEBUG UART

- Support for Debug UART interface (1.8V) via QUP12

**Figure 17: UART Interface**



## 2.1.13 RTC

- Supports 2V to 3.25V Cells
- No external resistor for current limit required
- 5 x 10uF Capacitors is placed inside the SOM for Sudden Momentary Power Loss (SMPL) not loose RTC contents.

## 2.1.14 BOOT CONTROL

### Boot Sequence Start

- Boot sequence starts when a low input trigger on keypad power on detect input (POWER\_ON net P2.89 on SOM connector PHONE\_ON\_N pin of PM8250 & PM8150B).



#### NOTE

- Signal should stay low until JTAG\_PS\_HOLD(SDM\_PS\_HOLD) is asserted from low to high or a minimum duration of 200ms

### Boot Device Control

- Boot system from UFS, SD Card or USB.
- Boot signals are internally pulled down.
- During development or factory production, boot from the USB0 port can be forced by using GPIO\_132 (FORCE\_USB\_BOOT).
- Logic state of Boot Configuration are latched during on processor resets out
- Each option holds a different boot sequence as described in the table below
- Each devices are tried on the order given on boot configuration option

**Table 6: Boot Configure Options**

FASTBOOT	GPIO#				Boot Sequence
	90	76	47	27	
0b0000	0	0	0	0	UFS HS G1 -> SD -> USB3.0 -> EDL(EDL path- USB only)
0b0001	0	0	0	1	SD -> UFS HS G1 -> EDL(EDL path- USB only)
0b0010	0	0	1	0	SD -> EDL(EDL path- USB only)
0b0011	0	0	1	1	USB -> EDL (EDL path - SD Then USB)
0b0100	0	1	0	0	QSPI -> EDL (EDL path - SD Then USB)
0b0101	0	1	0	1	SPI-> EDL (EDL path - SD Then USB)



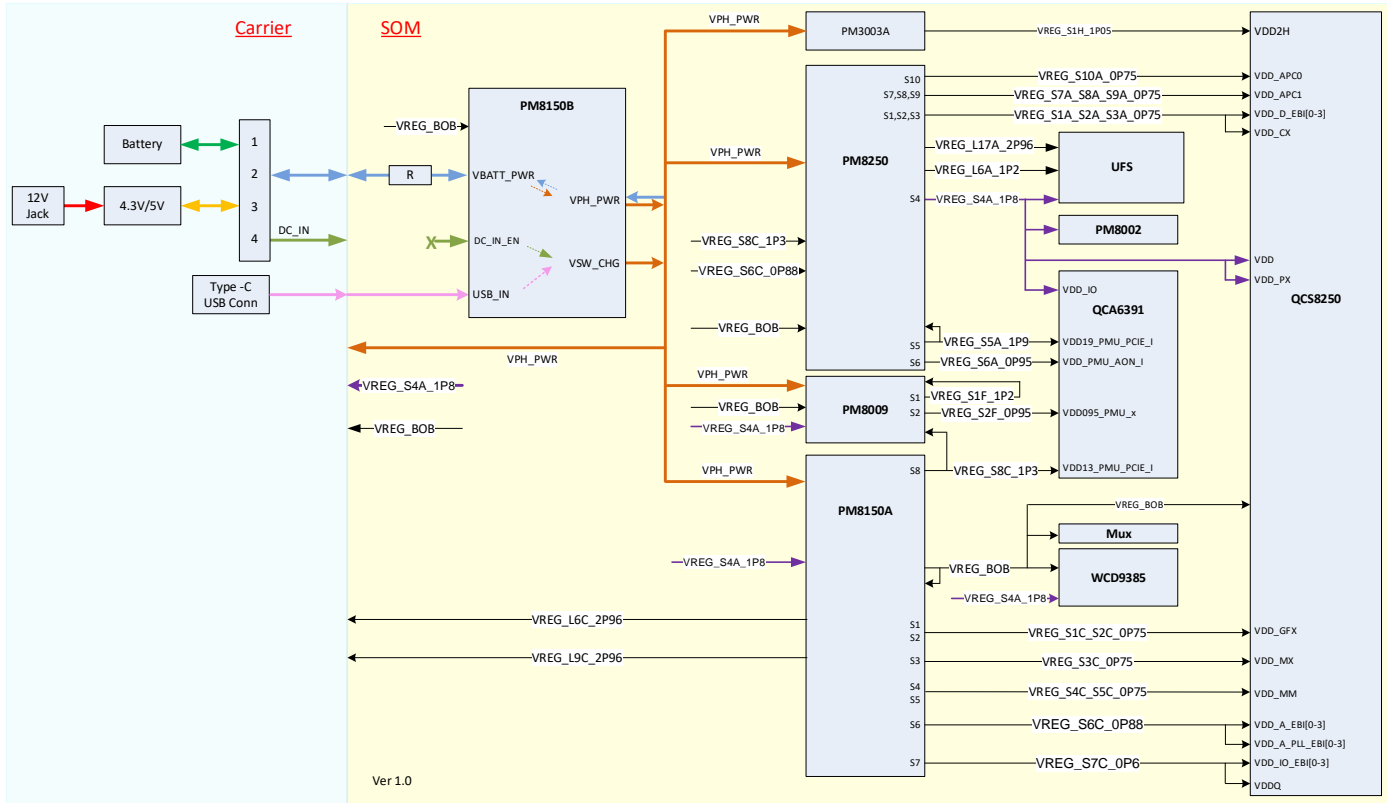
#### NOTE

- *Boot sequence will start only on a low input applied to keypad power on detect input.*
- *State of the Boot Config Pins are latched during APQ reset out*

### 2.1.15 POWER SUPPLY

- Power source from VBAT ranges from 3.2V to 4.5V (Single Cell Li-on Battery)
- Battery charging on the SOM through USB\_VBUS as charger power input
- Power supply for QCS8250 power is from PMICs and to other devices (WIFI, UFS, etc).
- SOM supplies VREG\_S4A\_1P8 (1.8V IO power), VREG\_L6C\_2P96 (SDCard IO) and VREG\_L9C\_2P96 (SD card Power)

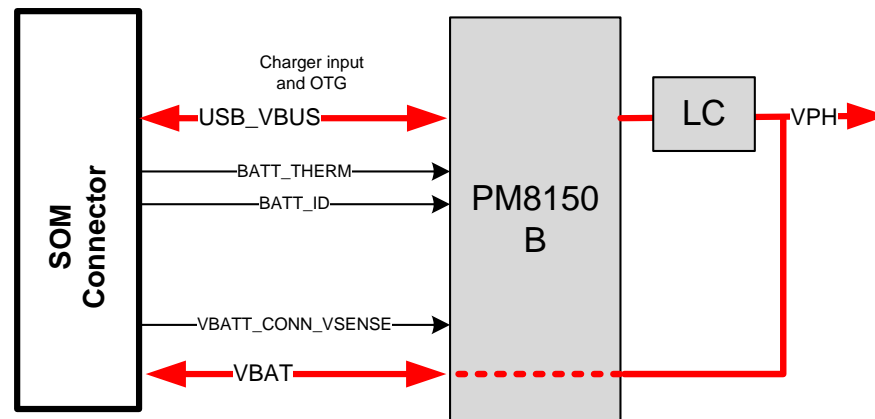
Figure 18: Power Scheme



## 2.1.16 CHARGER

- The SOM supports single cell lion charger
- Charge Current upto 6A
- Quick Charge 2.0, 3.0 and 4.0 hardware support
- USB Type-C and power delivery hardware support
- USB OTG and MHL/MyDP power support (1.5 A at +5-5.2 V)
- +3.6 V to +13.2 V operating input voltage range on USB\_VBUS with +28 V OVP
- BATT\_ID & BATT\_THERM are terminated inside SOM with 7.5K and 100K respectively to work with battery-less operation

**Figure 19: Charger**



## 2.1.17 REGULATOR OUTPUTS

- Supports several regulator outputs including SD card power, IO reference power etc
- LDOs
  - VREG\_L6C\_2P96
  - VREG\_L9C\_2P96
- SMPS out
  - VREG\_BOB
  - VREG\_S4A\_1P8
  - VPH\_PWR

Figure 20: Regulator Output

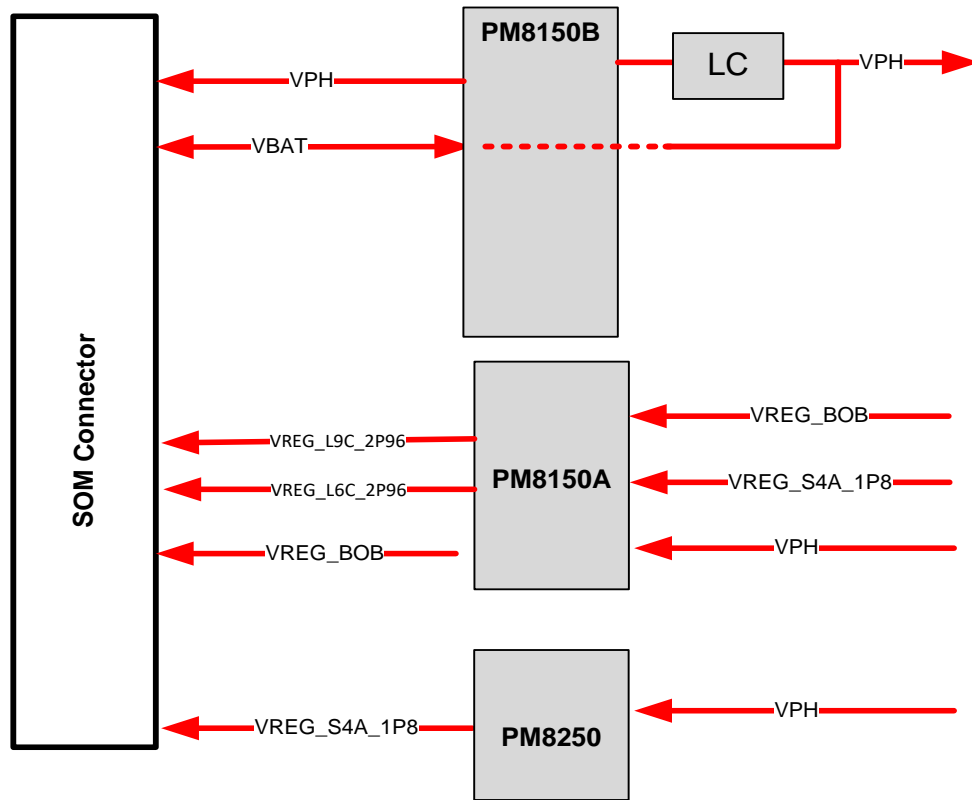


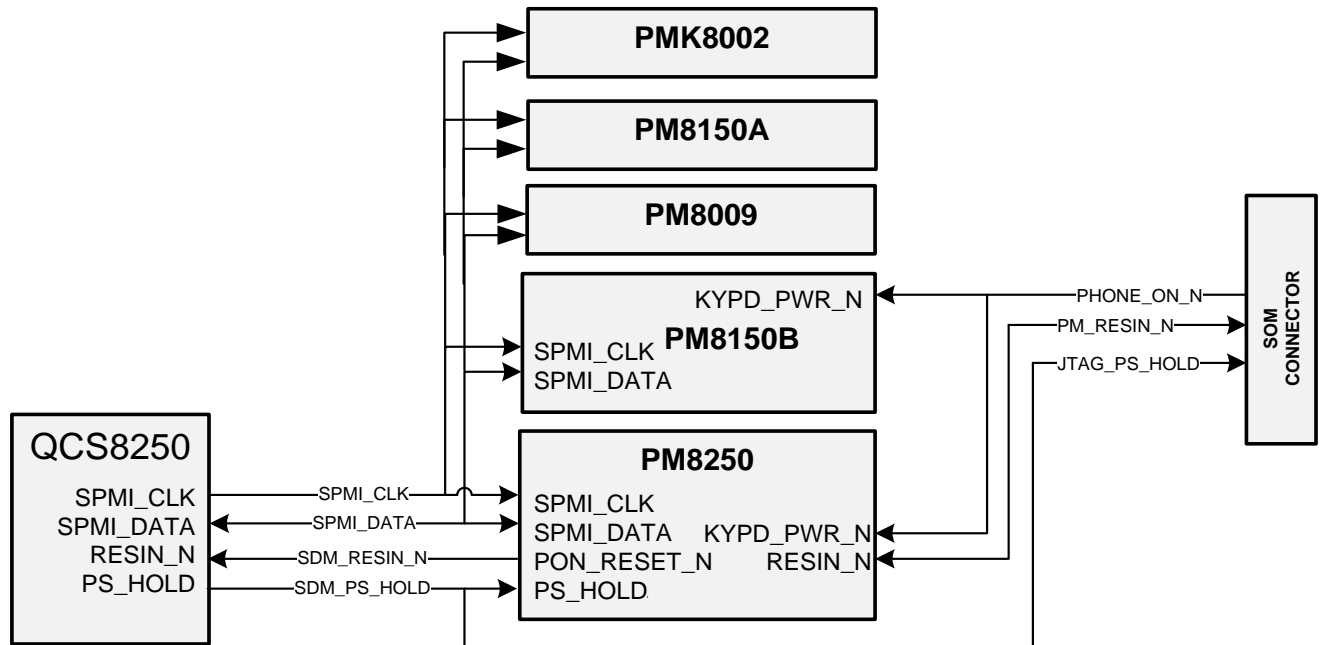
Table 7: Regulator Specifications

Regulator	Regulator input	Input Voltage	Default V	I rated Max (mA)	Range	Present load inside SOM (mA)	Comments
VREG_BOB	VPH	VBAT	3.3	3000	3.3-4	1700	3A capacity is when vph > 3.3V , if 3<VPH<3.3V only 2.5A available, Used for WIFI, SDCARD, UFS regulators
L6C	VREG_BOB	3.3	2.96	150	1.8-2.96	0	
L9C	VREG_BOB	3.3	2.96	600	2.704-2.96	0	
VREG_S4A_1P8	VPH	VBAT	1.8	3000	1.8V	2300	700mA Output

### 2.1.18 PMIC CONTROL

- PM8250, PM8150B, PM8150A, PMK8002 and PM8009 communicate to QCS8250 via SPMI interface
- PM\_RESIN\_N signal serves as reset input
- PHONE\_ON\_N serves power on trigger

Figure 21: PMIC Control



**NOTE**

- Internal Pull ups are present in the PMICs for PHONE\_ON\_N and PM\_RESIN\_N

## 2.1.19 GPIOs

- GPIOs can have multiple functions and QUP function
- QUP functions include UART, I2C and SPI
- 1 sensor core I3C
- All GPIOs are 1.8V level
- Only one protocol can be selected in one QUP engine at a time. For example, simultaneous UART and I2C functionality is no longer supported.
- Boot Configuration GPIOs must be taken care logic before processor resets out, Refer Boot Config section for Boot configurations
- Refer Appendix for GPIO list
- QUP I/Os use the following naming convention: qup\_lm[n]
- m indicates the lane number, and n is the instance number

**Table 8: QUP configurations**

QUP Lane	UART	I2C	SPI
QUP_L0	CTS	SDA	MISO
QUP_L1	RFR	SCL	MOSI
QUP_L2	Tx	–	SCLK
QUP_L3	Rx	–	CS_0
QUP_L4	–	–	CS_1
QUP_L5	–	–	CS_2
QUP_L6	–	–	CS_3



## 2.1.20 SENSOR CORE

- SOC has an integrated sensor subsystem called Snapdragon sensor core, which is dedicated to support low-power, always-on use cases
- The QCS8250 SoC's sensor core has a dedicated 1.0 MB L2/TCM cache.
- For sensor interrupts, any available MPM-capable GPIO can be routed as an interrupt to the Snapdragon sensor core subsystem.
- Sensor Core GPIOs are available on Pins SDM\_GPIO\_24\_OR\_160 & SDM\_GPIO\_25\_OR\_161 when GPIO\_162 is high else QUP GPIOs will be Selected

**Table 9: Sensor Core GPIOs**

Sensor Core	Function 1
SSC_0	SSC_I3C_1_SDA
SSC_1	SSC_I3C_1_SCL

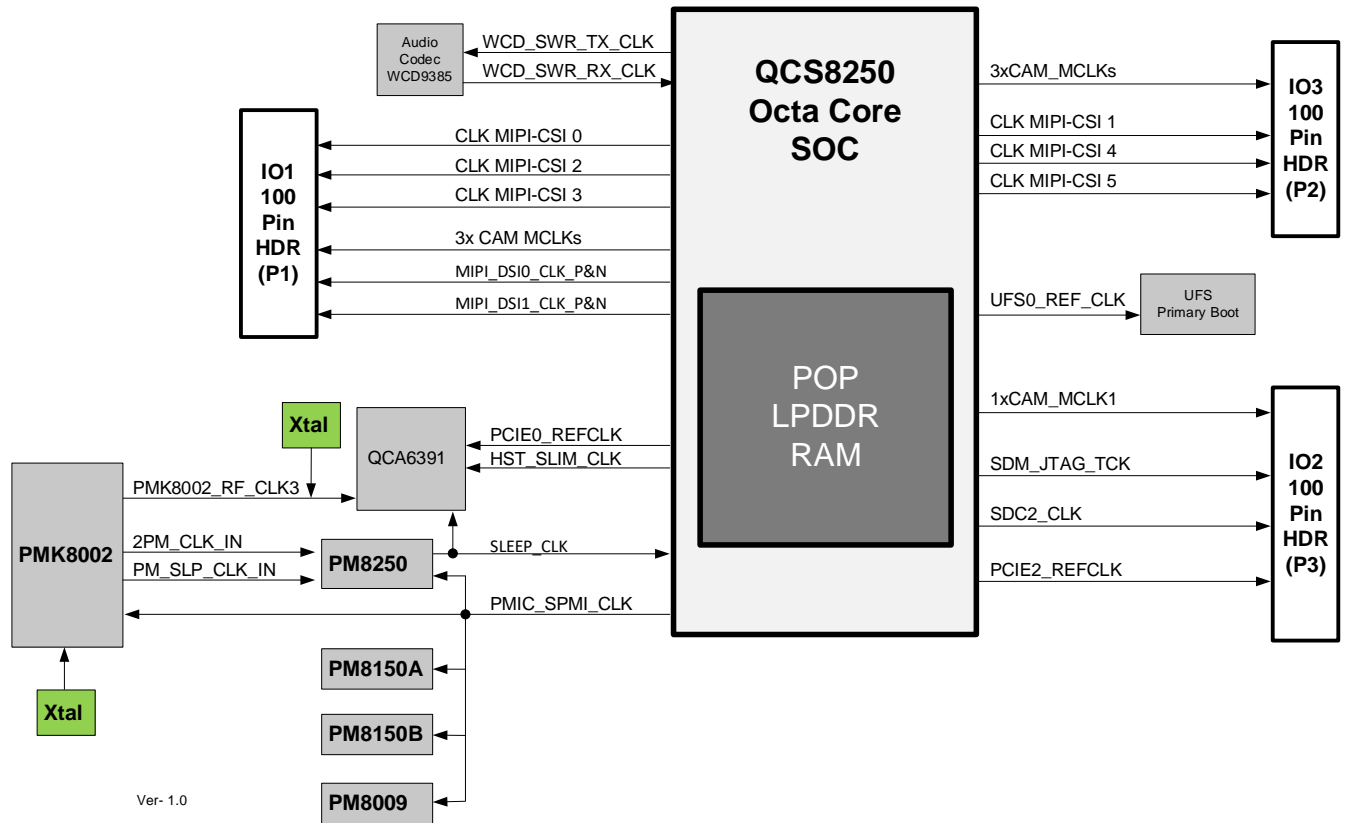
**Table 10: Sensor Core Mux**

Pin	GPIO_162 = 0	GPIO_162 = 1
SDM_GPIO_24_OR_160	GPIO_24	SSC_0
SDM_GPIO_25_OR_161	GPIO_25	SSC_1

### 2.1.21 CLOCK DISTRIBUTION NETWORK

- PMIC generates clock from 38.4MHz crystal and supplies clock to processor and other chips
- Processor supplies interface clocks

**Figure 22: Clock Distribution Network**



## 3. MECHANICAL SPECIFICATIONS

### 3.1 BOARD DIMENSIONS

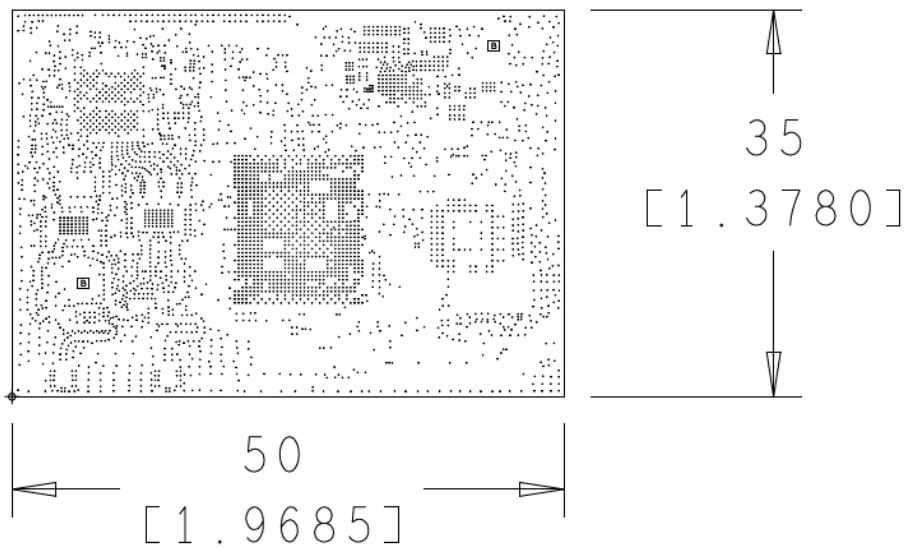
Dimensions : 50 × 35mm

Tolerance : +/-0.2mm

Layers : 14

PCB Thickness : 1mm

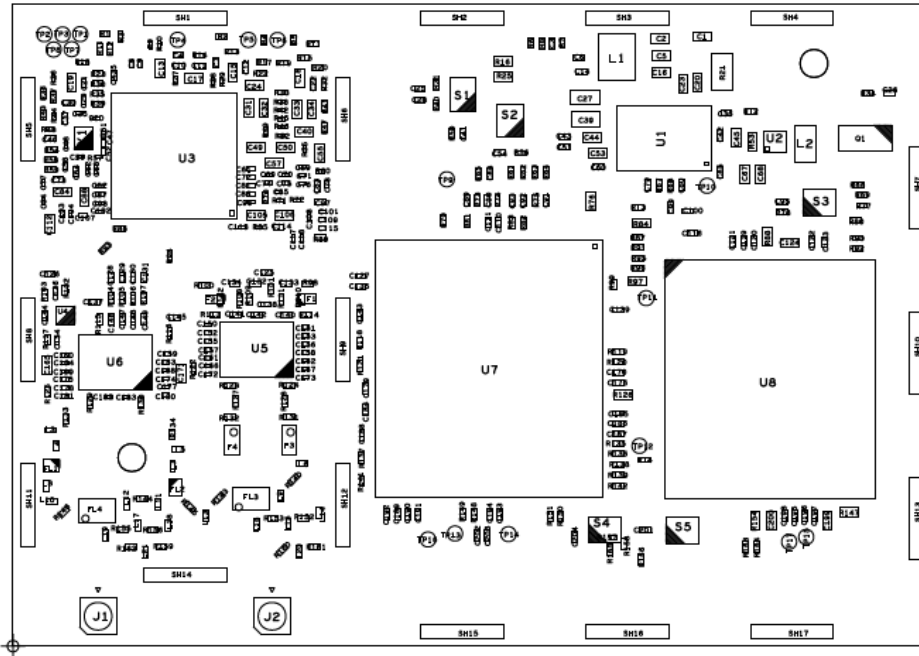
**Figure 23: Board Dimensions**



ALL DIMENSION ARE IN MM [INCH]

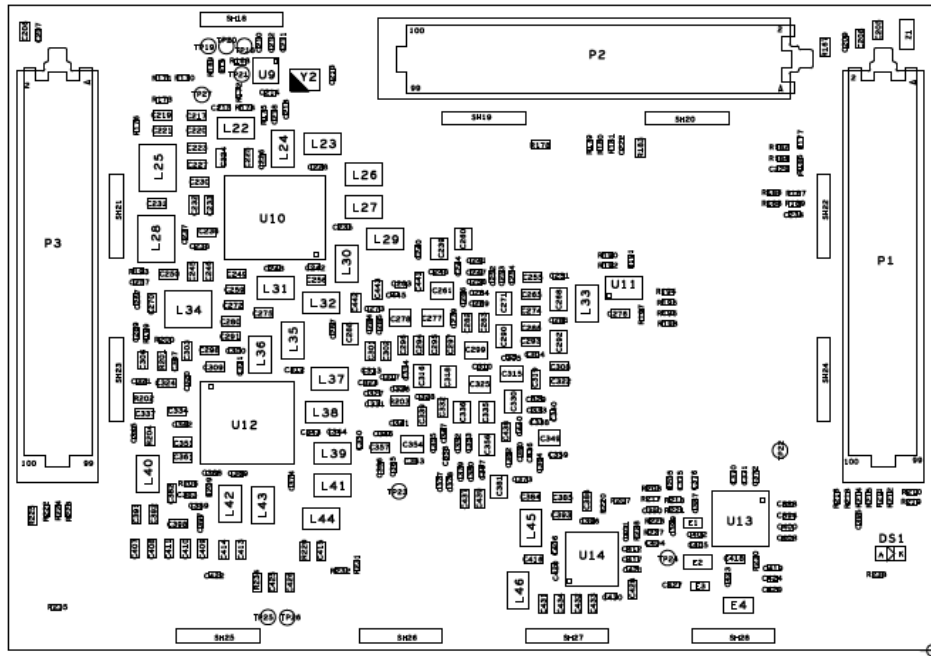
### 3.2 TOP FLOOR PLAN

Figure 24: Top Floor Plan



### 3.3 BOTTOM FLOOR PLAN

Figure 25: Bottom Floor Plan



# 4. APPENDIX A

## 4.1 SOM CONNECTORS

Manufacturer : Samtec

Manufacturer Part : ST4-50-1.50-L-D-P-TR

**Table 11: Connector IO interface 1 Pin out (Ref Des P1)**

Pin	Net	Comments	QUP
1	VBAT_CONN	Power input	
3	VBAT_CONN	Power input	
5	WCD_EAR_OUT_P	Audio	
7	WCD_EAR_OUT_M	Audio	
9	WCD_AUX_OUT_P	Audio	
11	WCD_AUX_OUT_M	Audio	
13	CDC_IN6_P	Audio	
15	CDC_IN7_P	Audio	
17	DMIC45_CLK	Audio	
19	GND		
21	MIPI_CSI2_B2_LANE3_P	Camera	
23	MIPI_CSI2_C2_LANE3_N	Camera	
25	GND	Camera	
27	MIPI_CSI2_A2_LANE2_N	Camera	
29	MIPI_CSI2_C1_LANE2_P	Camera	
31	GND	Camera	
33	MIPI_CSI2_A1_LANE1_P	Camera	
35	MIPI_CSI2_B1_LANE1_N	Camera	
37	GND	Camera	
39	MIPI_CSI2_A0_CLK_N	Camera	
41	MIPI_CSI2_NC_CLK_P	Camera	
43	GND	Camera	
45	MIPI_CSI2_C0_LANE0_N	Camera	
47	MIPI_CSI2_B0_LANE0_P	Camera	
49	GND		
51	MIPI_DSI1_LANE3_P	Display	
53	MIPI_DSI1_LANE3_N	Display	
55	GND	Display	
57	MIPI_DSI1_LANE2_P	Display	
59	MIPI_DSI1_LANE2_N	Display	
61	GND	Display	
63	MIPI_DSI1_LANE1_N	Display	
65	MIPI_DSI1_LANE1_P	Display	
67	GND	Display	
69	MIPI_DSI1_LANE0_P	Display	
71	MIPI_DSI1_LANE0_N	Display	
73	GND	Display	
75	MIPI_DSI1_CLK_N	Display	
77	MIPI_DSI1_CLK_P	Display	
79	WCD_HPH_REF_R		
81	CDC_IN2_P	Mic In	
83	WCD_HPH_R	Headphone Out	
85	WCD_HPH_REF_L	Headphone Out	
87	WCD_HPH_L	Headphone Out	
89	PHONE_ON_N_CON	Power ON	
91	PM_RESIN_N_CON	Vol-/ Reset	
93	SDM_GPIO_28	GPIO	QUP_L0(0 )
95	SDM_GPIO_29	GPIO	QUP_L1(0 )
97	VREG_S4A_1P8	1.8V Out	
99	VREG_S4A_1P8	1.8V Out	

Pin	Net	Comments	QUP
2	V3V3_CON	Power input	
4	VBAT_CONN	Power input	
6	CAM_MCLK2		
8	DMIC45_DATA		
10	CCI_I2C_SCL1		
12	CAM_MCLK0		
14	CCI_I2C_SDA1		
16	GND		
18	MIPI_CSIO_C0_LANE0_N	Camera	
20	MIPI_CSIO_B0_LANE0_P	Camera	
22	GND	Camera	
24	MIPI_CSIO_A0_CLK_N	Camera	
26	MIPI_CSIO_NC_CLK_P	Camera	
28	GND	Camera	
30	MIPI_CSIO_A1_LANE1_P	Camera	
32	MIPI_CSIO_B1_LANE1_N	Camera	
34	GND	Camera	
36	MIPI_CSIO_A2_LANE2_N	Camera	
38	MIPI_CSIO_C1_LANE2_P	Camera	
40	GND	Camera	
42	MIPI_CSIO_C2_LANE3_N	Camera	
44	MIPI_CSIO_B2_LANE3_P	Camera	
46	GND	Camera	
48	MIPI_CSIO_NC_CLK_P	Camera	
50	MIPI_CSIO_A0_CLK_N	Camera	
52	GND	Camera	
54	MIPI_CSIO_B0_LANE0_P	Camera	
56	MIPI_CSIO_C0_LANE0_N	Camera	
58	GND	Camera	
60	MIPI_CSIO_A1_LANE1_P	Camera	
62	MIPI_CSIO_B1_LANE1_N	Camera	
64	GND		
66	CAM3_RST_N		
68	CAM_MCLK3		
70	GND		
72	MIPI_DSIO_LANE3_N	Display	
74	MIPI_DSIO_LANE3_P	Display	
76	GND	Display	
78	MIPI_DSIO_LANE2_N	Display	
80	MIPI_DSIO_LANE2_P	Display	
82	GND	Display	
84	MIPI_DSIO_LANE1_P	Display	
86	MIPI_DSIO_LANE1_N	Display	
88	GND	Display	
90	MIPI_DSIO_LANE0_P	Display	
92	MIPI_DSIO_LANE0_N	Display	
94	GND	Display	
96	MIPI_DSIO_CLK_P	Display	
98	MIPI_DSIO_CLK_N	Display	
100	GND	Display	

**Table 12: Connector IO interface 2 Pin out (Ref Des P3)**

Pin	Net	Comments	QUP
1	VBAT_CONN	Power input	
3	VBAT_CONN	Power input	
5	CAM2_RST_N		
7	CAM0_STANDBY_N		
9	USB_CC2_R	USB	
11	FORCE_USB_BOOT_MCLK		
13	SDM_FAST_BOOT_0		
15	CAM0_RST_N		
17	FLASH_STROBE_EN		
19	CCI_I2C_SDA0		
21	CCI_I2C_SCL0		
23	GND		
25	USB0_SS_RX1_M	USB	
27	USB0_SS_RX1_P	USB	
29	GND	USB	
31	USB0_HS_DP	USB	
33	USB0_HS_DM	USB	
35	GND	USB	
37	USB2_HS_DP	USB	
39	USB2_HS_DM	USB	
41	GND	USB	
43	TS_I2C_SCL	Touch	
45	TS_I2C_SDA	Touch	
47	BACKLIGHT_EN	Backlight Enable Out	
49	SDM_GPIO_5		QUP_L1(1)
51	TS_INT_N	Touch	
53	PM8150A_GPIO_06_OR_10	PMIC GPIO/PWM Out	
55	TS_RESET_N	Touch	
57	DISP0_RESET_N	Display Reset	
59	SDM_GPIO_4		QUP_L0(1)
61	SDM_DEBUG_UART_TX	Debug UART	
63	SDM_DEBUG_UART_RX	Debug UART	
65	GND		
67	WSA_SWR_DATA	Soundwire	
69	WSA_SWR_CLK	Soundwire	
71	GND		
73	PCIE2_REFCLK_P	pcie	
75	PCIE2_REFCLK_M	pcie	
77	GND	pcie	
79	PCIE2_TX0_P	pcie	
81	PCIE2_TX0_M	pcie	
83	GND	pcie	
85	PCIE2_RX0_P	pcie	
87	PCIE2_RX0_M	pcie	
89	GND	pcie	
91	PCIE2_CLK_REQ_N	pcie	
93	PCIE2_WAKE_N	pcie	
95	PCIE2_RST_N	pcie	
97	SDM_GPIO_30		QUP_L2(0)
99	SDM_GPIO_31		QUP_L3(0)

Pin	Net	Comments	QUP
2	VBAT_CONN	Power input	
4	VBAT_CONN	Power input	
6	FLASH_STROBE_TRIG		
8	WDOG_DISABLE		
10	KYPD_VOLP_N_CON		
12	SDM_GPIO_52_OR_139		QUP_L0(17)
14	USB_VBUS		
16	SDM_GPIO_55_OR_141		QUP_L3(17)
18	SDM_GPIO_53_OR_140		QUP_L1(17)
20	SDM_GPIO_54_OR_138		QUP_L2(17)
22	USB_CC1	USB	
24	CAM_MCLK4		
26	USB_SBU1	USB	
28	USB_SBU2	USB	
30	GND	USB	
32	USB0_SS_TX1_M	USB	
34	USB0_SS_TX1_P	USB	
36	GND	USB	
38	USB0_SS_RX0_M	USB	
40	USB0_SS_RX0_P	USB	
42	GND	USB	
44	USB0_SS_TX0_M	USB	
46	USB0_SS_TX0_P	USB	
48	SDM_GPIO_24_OR_160		QUP_L0(8)
50	SDM_GPIO_25_OR_161		QUP_L1(8)
52	SDM_RESOUT_N		
54	CAM4_RST_N		
56	SDM_FAST_BOOT_1		
58	JTAG_PS_HOLD		
60	SD_UFS_CARD_DET_N	Sdcard	
62	VREG_L6C_2P96	Sdcard	
64	SDC2_DATA_2	Sdcard	
66	SDC2_DATA_1	Sdcard	
68	SDC2_CLK	Sdcard	
70	SDC2_DATA_3	Sdcard	
72	SDC2_CMD	Sdcard	
74	SDC2_DATA_0	Sdcard	
76	VREG_L9C_2P96	Sdcard	
78	SDM_JTAG_TRST_N	jtag	
80	SDM_JTAG_SRST_N	jtag	
82	SDM_JTAG_TDO	jtag	
84	SDM_JTAG_TDI	jtag	
86	SDM_JTAG_TCK	jtag	
88	SDM_JTAG_TMS	jtag	
90	WCD_HS_DET_L	Headset Detect	
92	SDM_GPIO_41		QUP_L1(14)
94	CAM2_STANDBY_N		
96	SOM_OPTION	Options (Auto Boot/Charger Disable)	
98	VCOIN_R	Options	
100	USB_VBUS_R	Options	

Table 13: Connector IO interface 3 Pin out (Ref Des P2)

Pin	Net	Comments	QUP
1	GND	Camera	
3	MIPI_CSI4_C1_LANE2_P	Camera	
5	MIPI_CSI4_A2_LANE2_N	Camera	
7	GND	Camera	
9	MIPI_CSI4_A1_LANE1_P	Camera	
11	MIPI_CSI4_B1_LANE1_N	Camera	
13	GND	Camera	
15	MIPI_CSI4_A0_CLK_N	Camera	
17	MIPI_CSI4_NC_CLK_P	Camera	
19	GND	Camera	
21	DMIC23_CLK	audio	
23	DMIC23_DATA	audio	
25	GND		
27	VCOIN	RTC	
29	MIPI_CSI4_C2_LANE3_N	Camera	
31	MIPI_CSI4_B2_LANE3_P	Camera	
33	GND	Camera	
35	MIPI_CSI4_C0_LANE0_N	Camera	
37	MIPI_CSI4_B0_LANE0_P	Camera	
39	CABC_CON		
41	GND		
43	CAM_MCLK6		
45	CCI_I2C_SDA2		
47	CCI_I2C_SCL2		
49	VBAT_CONN	Power	
51	VBAT_CONN	Power	
53	VREG_BOB	LDO	
55	DMIC01_CLK	audio	
57	DMIC01_DATA	audio	
59	GND_P59		
61	MIPI_CSI5_A1_LANE1_P	Camera	
63	MIPI_CSI5_B1_LANE1_N	Camera	
65	GND	Camera	
67	MIPI_CSI5_NC_CLK_P	Camera	
69	MIPI_CSI5_A0_CLK_N	Camera	
71	GND	Audio	
73	CDC_IN4_M	Audio	
75	CDC_IN4_P	Audio	
77	CDC_IN5_P	Audio	
79	CDC_IN5_M	Audio	
81	MIC_BIAS1	Audio	
83	GND	Audio	
85	MIPI_CSI5_B0_LANE0_P	Audio	
87	MIPI_CSI5_C0_LANE0_N	Audio	
89	GND		
91	MIPI_CSI5_C1_LANE2_P	Camera	
93	MIPI_CSI5_A2_LANE2_N	Camera	
95	GND	Camera	
97	MIPI_CSI5_B2_LANE3_P	Camera	
99	MIPI_CSI5_C2_LANE3_N	Camera	

Pin	Net	Comments	QUP
2	GND	Camera	
4	MIPI_CSI1_A0_CLK_N	Camera	
6	MIPI_CSI1_NC_CLK_P	Camera	
8	GND	Camera	
10	MIPI_CSI1_C0_LANE0_N	Camera	
12	MIPI_CSI1_B0_LANE0_P	Camera	
14	GND	Camera	
16	MIPI_CSI1_A1_LANE1_P	Camera	
18	MIPI_CSI1_B1_LANE1_N	Camera	
20	GND	Camera	
22	MIPI_CSI1_A2_LANE2_N	Camera	
24	MIPI_CSI1_C1_LANE2_P	Camera	
26	GND	Camera	
28	MIPI_CSI1_C2_LANE3_N	Camera	
30	MIPI_CSI1_B2_LANE3_P	Camera	
32	GND	Camera	
34	USB2_SS_RX_M	USB	
36	USB2_SS_RX_P	USB	
38	GND	USB	
40	USB2_SS_TX_M	USB	
42	USB2_SS_TX_P	USB	
44	GND	USB	
46	CAM_MCLK5		
48	CAM_MCLK1		
50	CAM1_STANDBY_N		
52	CAM1_RST_N		
54	GND		
56	MI2S2_WS		
58	USB_VBUS	Power and battery	
60	USB_VBUS	Power and battery	
62	USB_VBUS	Power and battery	
64	VBAT_CONN	Power and battery	
66	VBAT_CONN	Power and battery	
68	GND	Power and battery	
70	VPH_PWR	Power and battery	
72	VPH_PWR	Power and battery	
74	VPH_PWR	Power and battery	
76	BATT_THERM	Power and battery	
78	BATT_ID	Power and battery	
80	VBATT_CONN_VSENSE_M	Power and battery	
82	VBATT_CONN_VSENSE_P	Power and battery	
84	MIC_BIAS3		
86	MIC_BIAS4		
88	GND		
90	MI2S2_SCK		
92	MI2S2_DATA0		
94	MI2S2_DATA1_REF_CLK		
96	CCI_I2C_SDA3_CON		
98	CCI_I2C_SCL3_CON		
100	CAM5_RST_N_CON		

## 4.2 IO CONNECTOR GPIOs

- Refer processor datasheet for more details

**Table 14: IO CONNECTOR GPIOs**

IO interface	pin	Net Name	Comments	QUP	QUP Number	GPIO	I2X/UART	Wake Capable
1	6	CAM_MCLK2				GPIO_96		
1	10	CCI_I2C_SCL1				GPIO_104	I2C	Y
1	12	CAM_MCLK0				GPIO_94		
1	14	CCI_I2C_SDA1				GPIO_103	I2C	Y
1	66	CAM3_RST_N				GPIO_109		Y
1	68	CAM_MCLK3				GPIO_97		
1	93	SDM_GPIO_28	GPIO	QUP_L0(0)	0	GPIO_28	I3C	Y
1	95	SDM_GPIO_29	GPIO	QUP_L1(0)	0	GPIO_29	I3C	
2	5	CAM2_RST_N		QUP_L0(14)	14	GPIO_40	I3C	Y
2	6	FLASH_STROBE_TRIG				GPIO_110		Y
2	7	CAM0_STANDBY_N		QUP_L2(1)	1	GPIO_6		
2	8	WDOG_DISABLE		QUP_L3(9)	9	GPIO_128		Y
2	12	SDM_GPIO_52_OR_139		QUP_L0(17)	17	GPIO_52	UART	
2	13	SDM_FAST_BOOT_0		QUP_L3(8)	8	GPIO_27		Y
2	15	CAM0_RST_N		QUP_L3(14)	14	GPIO_43		Y
2	16	SDM_GPIO_55_OR_141		QUP_L3(17)	17	GPIO_55	UART	Y
2	17	FLASH_STROBE_EN				GPIO_111		Y
2	18	SDM_GPIO_53_OR_140		QUP_L1(17)	17	GPIO_53	UART	
2	19	CCI_I2C_SDA0				GPIO_101	I2C	
2	20	SDM_GPIO_54_OR_138		QUP_L2(17)	17	GPIO_54	UART	
2	21	CCI_I2C_SCL0				GPIO_102	I2C	
2	24	CAM_MCLK4				GPIO_98		
2	43	TS_I2C_SCL	Touch	QUP_L1(13)	13	GPIO_37	I2C	
2	45	TS_I2C_SDA	Touch	QUP_L0(13)	13	GPIO_36	I2C	
2	47	BACKLIGHT_EN	Backlight Enable Out	QUP_L3(13)	13	GPIO_39		Y
2	48	SDM_GPIO_24_OR_160		QUP_L0(8)	8	GPIO_24	I3C	Y
2	49	SDM_GPIO_5		QUP_L1(1)	1	GPIO_5	I2C	
2	50	SDM_GPIO_25_OR_161		QUP_L1(8)	8	GPIO_25	I3C	
2	51	TS_INT_N	Touch	QUP_L3(18)	18	GPIO_59	UART	Y
2	54	CAM4_RST_N		QUP_L1(10)	10	GPIO_130		
2	56	SDM_FAST_BOOT_1		QUP_L3(15)	15	GPIO_47		Y
2	59	SDM_GPIO_4		QUP_L0(1)	1	GPIO_4	I2C	Y
2	60	SD_UFS_CARD_DET_N	Sdcard			GPIO_77		Y
2	61	SDM_DEBUG_UART_TX	Debug UART	QUP_L2(12)	12	GPIO_34	UART	
2	63	SDM_DEBUG_UART_RX	Debug UART	QUP_L3(12)	12	GPIO_35	UART	Y



IO interface	pin	Net Name	Comments	QUP	QUP Number	GPIO	I2X/UART	Wake Capable
2	91	PCIE2_CLK_REQ_N	pcie			GPIO_86		Y
2	92	SDM_GPIO_41		QUP_L1(14)	14	GPIO_41	I3C	
2	93	PCIE2_WAKE_N	pcie			GPIO_87		Y
2	94	CAM2_STANDBY_N		QUP_L0(4)	4	GPIO_8		
2	95	PCIE2_RST_N	pcie			GPIO_85		
2	97	SDM_GPIO_30		QUP_L2(0)	0	GPIO_30		
2	99	SDM_GPIO_31		QUP_L3(0)	0	GPIO_31		Y
3	43	CAM_MCLK6				GPIO_100		Y
3	45	CCI_I2C_SDA2				GPIO_105	I2C	
3	46	CAM_MCLK5				GPIO_99		
3	47	CCI_I2C_SCL2				GPIO_106	I2C	
3	48	CAM_MCLK1				GPIO_95		
3	50	CAM1_STANDBY_N		QUP_L3(1)	1	GPIO_7		Y
3	52	CAM1_RST_N		QUP_L1(4)	4	GPIO_9		

## 4.3 ELECTRICAL SPECIFICATIONS OF PINS

**Table 15: IO CONNECTOR Power specifications**

Voltage rail	Min V	Typical V	Max V
VBAT	3.2	3.8V	4.5
1.8V Out	1.7	1.8	1.9
SDCard Power	2.7	2.95	3.6
SDC2 IO	1.7/2.7	1.8/2.95	1.9/3.04
VCOIN	2	3	3.25
USB_VBUS	3.6	5	13.2

**Table 16: IO specifications**

1.8V GPIO	Min V	Typical V	Max V
VIH	1.26	-	2.1
VIL	-0.3	-	0.54
VOH	1.35	-	1.8
VOL	0	-	0.45
SDCard IO 2.95V	Min V	Typical V	Max V
VIH	1.84	-	3.25
VIL	-0.3	-	0.735
VOH	2.21	-	2.95
VOL	0	-	0.36
SDCard IO 1.8V	Min V	Typical V	Max V
VIH	1.27	-	2
VIL	-0.3	-	0.58
VOH	1.4	-	-
VOL	-	-	0.45

## 4.4 RF CONNECTORS

Manufacturer	: I-PEX
Manufacturer Part	: 20449-001E-03
Description	: MHF4 Coaxial RF connector
Functions	: Wi-Fi, Bluetooth



### CAUTION

Make sure that RF cable crimps are not touching any components nearby after assembled.

## 5. CONTACT INFORMATION

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